

IN THE CLAIMS:

Amendments to the Claims

Please amend claims 2-6 as shown below.

Listing of Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (original) A plasma processing apparatus provided with a holding stage of a system in which a temperature of an electrode block is controlled so as to control a temperature of a semiconductor wafer, wherein said electrode block is provided with at least first and second independent temperature control means on the inner and outer sides thereof and, a slit for suppressing heat transfer is provided in said electrode block between said first and second independent temperature control means.
2. (currently amended) A ~~The~~ plasma processing apparatus according to claim 1, wherein said slit for suppressing heat transfer is formed substantially concentrically.
3. (currently amended) A ~~The~~ plasma processing apparatus according to claim 1, wherein a heater is provided on the backside of said electrode block.
4. (currently amended) A ~~The~~ plasma processing apparatus according to claim 1, wherein a heater is built in said electrode block.
5. (currently amended) A ~~The~~ plasma processing apparatus according to claim 1, wherein said electrode block is provided, on the surface thereof, with a dielectric film.

6. (currently amended) A-The plasma processing apparatus according to claim 1, wherein said electrode block is provided with temperature sensors and temperature control is performed on the basis of information from said temperature sensors.